# 15 A, 600 V, STEALTH Diode

#### Description

The ISL9R1560PF2 is a STEALTH diode optimized for low loss performance in high frequency hard switched applications. The STEALTH family exhibits low reverse recovery current ( $I_{RR}$ ) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low  $I_{RR}$  and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

#### Features

- Stealth Recovery,  $t_{rr} = 29.4$  ns (@  $I_F = 15$  A)
- Max. Forward Voltage,  $V_F = 2.2 \text{ V}$  (@  $T_C = 25^{\circ}\text{C}$ )
- 600 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

- Hard Switched PFC Boost Diode
- UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = $25^{\circ}$ C unless otherwise noted)

Rating	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600	V
Working Peak Reverse Voltage	V <sub>RWM</sub>	600	V
DC Blocking Voltage	V <sub>R</sub>	600	V
Average Rectified Forward Current $(T_C = 25^{\circ}C)$	I <sub>F(AV)</sub>	15	A
Repetitive Peak Surge Current (20 kHz Square Wave)	I <sub>FRM</sub>	30	A
Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz)	I <sub>FSM</sub>	200	A
Power Dissipation	PD	37	W
Avalanche Energy (1 A, 40 mH)	E <sub>AVL</sub>	20	mJ
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	–55 to 175	°C
Maximum Temperature for Soldering Leads at 0.063 in (1.6 mm) from Case for 10s	ΤL	300	°C

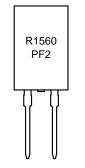
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



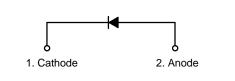


CASE 221AS

#### MARKING DIAGRAM



R1560PF2 = Specific Device Marking



### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Tape Width	Quantity
ISL9R1560PF2	R1560PF2	TO-220F-2L	N/A	50 Units

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF STATE C	HARACTERISTICS			•		
I <sub>R</sub>	Instantaneous Reverse Current	rrent $V_R = 600 \text{ V}, \text{ T}_C = 25^{\circ}\text{C}$	-	-	100	μΑ
		$V_{R} = 600 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	-	1.0	mA
ON STATE CH	IARACTERISTICS				•	
VF	Instantaneous Forward Voltage	I <sub>F</sub> = 15 A, T <sub>C</sub> = 25°C	-	1.8 2.2	V	
		I <sub>F</sub> = 15 A, T <sub>C</sub> = 125°C	-	1.65	2.0	V
OYNAMIC CH	ARACTERISTICS				•	
CJ	Junction Capacitance	I <sub>F</sub> = 0 A, V <sub>R</sub> = 10 V	-	62	-	pF
	CHARACTERISTICS					
t <sub>rr</sub>	Reverse Recovery Time	$I_F = 1 \text{ A}, \text{ dI}_F/\text{dt} = 100 \text{ A}/\mu\text{s}, \\ V_R = 30 \text{ V}$	-	25	30	ns
		$I_{F} = 15 \text{ A}, \text{ d}I_{F}/\text{d}t = 100 \text{ A}/\mu\text{s}, \\ V_{R} = 30 \text{ V}$	-	35	40	ns
t <sub>rr</sub>	Reverse Recovery Time	$I_{F} = 15 \text{ A},$ dI <sub>F</sub> /dt = 200 A/µs, V <sub>R</sub> = 390 V, T <sub>C</sub> = 25°C	-	29.4	-	ns
l <sub>rr</sub>	Maximum Reverse Recovery Current		-	3.5	-	Α
Q <sub>rr</sub>	Reverse Recovered Charge		-	57	-	nC
t <sub>rr</sub>	Reverse Recovery Time	$I_{F} = 15 \text{ A},$ $dI_{F}/dt = 200 \text{ A}/\mu\text{s},$ $V_{R} = 390 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	90	-	ns
S	Softness Factor (t <sub>b</sub> /t <sub>a</sub> )		-	2.0	-	
l <sub>rr</sub>	Maximum Reverse Recovery Current		-	5.0	-	Α
Q <sub>rr</sub>	Reverse Recovered Charge		-	275	-	nC
t <sub>rr</sub>	Reverse Recovery Time	$I_{F} = 15 \text{ A},$ dI <sub>F</sub> /dt = 800 A/µs, V <sub>R</sub> = 390 V, T <sub>C</sub> = 125°C	-	52	-	ns
S	Softness Factor (t <sub>b</sub> /t <sub>a</sub> )		-	1.36	_	
l <sub>rr</sub>	Maximum Reverse Recovery Current		-	13.5	-	Α
Q <sub>rr</sub>	Reverse Recovered Charge		-	390	-	nC
dl <sub>M</sub> /dt	Maximum di/dt during t <sub>b</sub>		_	800	_	A/μs

$R_{\thetaJC}$	Thermal Resistance Junction to Case		-	-	4.1	°C/W
$R_{\thetaJA}$	Thermal Resistance Junction to Ambient	TO-247	-	-	70	°C/W

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL PERFORMANCE CHARACTERISTICS**

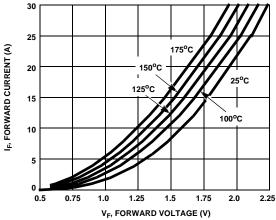


Figure 1. Forward Current vs. Forward Voltage

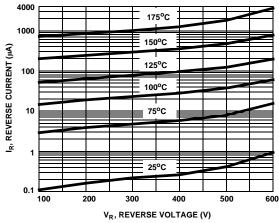


Figure 2. Reverse Current vs. Reverse Voltage

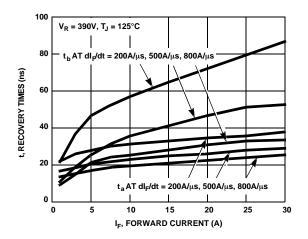


Figure 3. t<sub>a</sub> and t<sub>b</sub> Curves vs. Forward Current

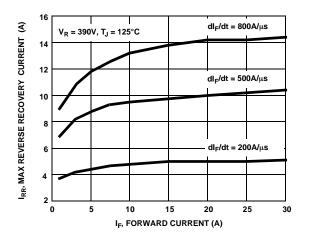


Figure 5. Maximum Reverse Recovery Current vs. **Forward Current** 

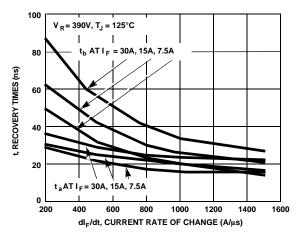


Figure 4. t<sub>a</sub> and t<sub>b</sub> Curves vs. dl<sub>F</sub>/dt

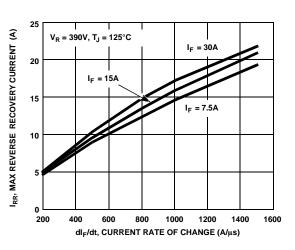


Figure 6. Maximum Reverse Recovery Current vs. dl<sub>F</sub>/dt

#### **TYPICAL PERFORMANCE CHARACTERISTICS**

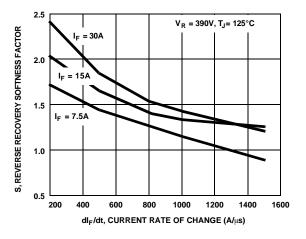


Figure 7. Reverse Recovery Softness Factor vs. dl<sub>F</sub>/dt

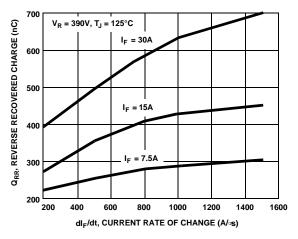


Figure 8. Reverse Recovered Charge vs. dl<sub>F</sub>/dt

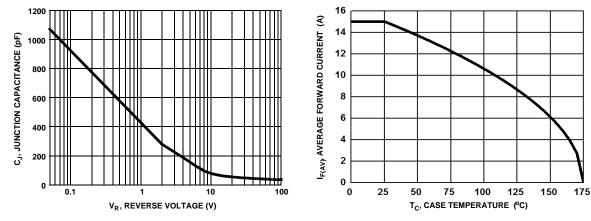


Figure 9. Junction Capacitance vs. Reverse Voltage

Figure 10. DC Current Derating Curve

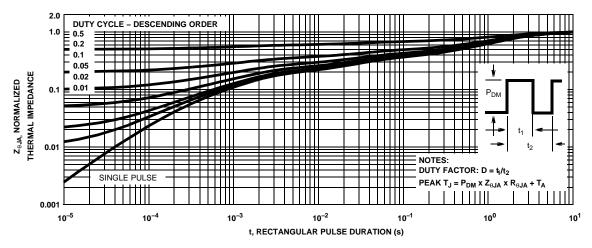


Figure 11. Normalized Maximum Transient Thermal Impedance

### **TEST CIRCUIT AND WAVEFORMS**

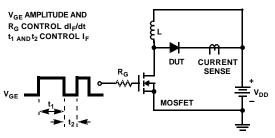


Figure 12. Test Circuit

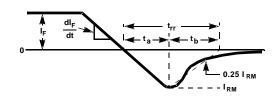


Figure 13. t<sub>rr</sub> Waveforms and Definitions

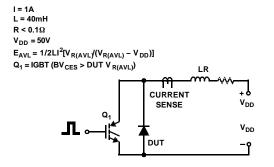


Figure 14. Avalanche Energy Test Circuit

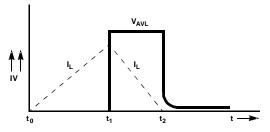
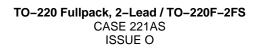
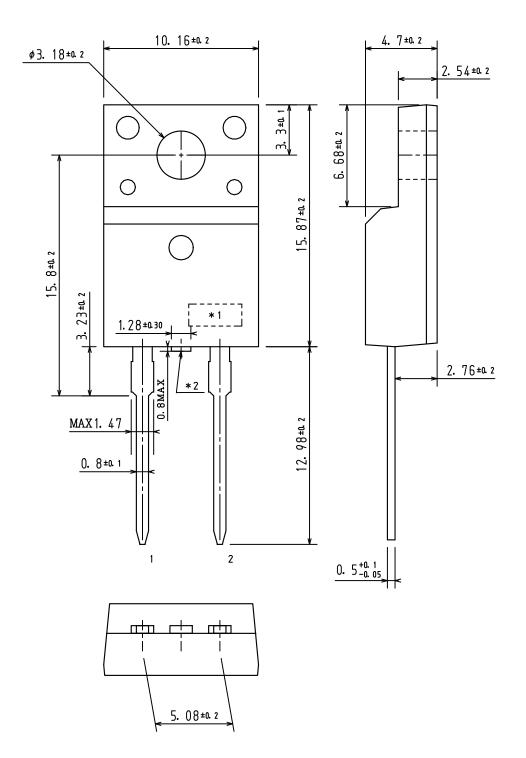


Figure 15. Avalanche Current and Voltage Waveforms

### PACKAGE DIMENSIONS





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